


WF-1310-10G	
Wafer for Fabrication of Temperature Stable High-Speed Lasers at 1240-1320nm	
	<p><b>Features:</b></p> <ul style="list-style-type: none"> <li>• Quantum dot (QD) active area</li> <li>• 1240-1320nm spectral range</li> <li>• Cooling-free operation of DFB lasers</li> <li>• Isolator-free operation of DFB lasers</li> </ul> <hr/> <p><b>Applications:</b></p> <ul style="list-style-type: none"> <li>• Fabry-Pérot and DFB lasers for                             <ul style="list-style-type: none"> <li>• FTTx (including EPON, GPON, 10G PON, WDM PON, etc.)</li> <li>• Telecom</li> <li>• etc.</li> </ul> </li> </ul>
	DATE: 19 <sup>th</sup> Jan 2009

SPECIFICATIONS					
Wafer Parameters	Symbol	Min.	Typ.	Max.	Unit
Size			76.2		mm
Surface defect density (0.7-10 $\mu\text{m}^2$ size)			50	100	cm <sup>-2</sup>
Haze			50	100	ppm
PL peak position (in wafer center)		1295	1300	1305	nm
PL peak homogeneity across a wafer			10	12	nm
Layer thickness tolerance				5	%
Layer composition tolerance				5	%
<i>n</i> -doping homogeneity across the wafer			2	5	%
<i>p</i> -doping homogeneity across the wafer			50	60	%
BA Laser Parameters					
Test conditions: 1mm laser length, 100 $\mu\text{m}$ laser width, pulse operation, 25°C					
Threshold current density	$j_{th}$		550	600	A/cm <sup>2</sup>
Differential efficiency	$\eta$		0.35		W/A
Lasing wavelength	$\lambda_{las}$	1300	1310	1320	nm
Threshold current characteristic temperature (25-85°C)	$T_0$	300	500		K
Differential efficiency characteristic temperature (25-85°C)	$T_1$	1000	2000		K
Temperature wavelength shift		0.43	0.5	0.57	nm/K
Serial resistance			0.1	0.2	m $\Omega\text{cm}^2$
Cut-off voltage			1.15	1.2	V
Far-field (FWHM, fast axis)			50	55	degree

## Layer description

Layer	Material	Group	Repeat	Mole fraction (x)		Thickness (nm)	Type	Dopant
				start	finish			
12	GaAs					200	P	C
11	Al(x)Ga(1-x)As			0.35	0	20	P	C
10	Al(x)Ga(1-x)As			0.35		1000	P	C
9	Al(x)Ga(1-x)As			0.35		500	P	C
8	GaAs	1	10			35		
7	In(x)Ga(1-x)As	1	10	0.15		5		
6	InAs	1	10			0.8		
5	GaAs					35		
4	Al(x)Ga(1-x)As			0.35		500	N	Si
3	Al(x)Ga(1-x)As			0.35		1000	N	Si
2	Al(x)Ga(1-x)As			0	0.35	20	N	Si
1	GaAs					500	N	Si
0	GaAs substrate	N+ GaAs 3 inch						

## Typical operation of DFB laser (600µm long) at 10Gbps

